

## Features

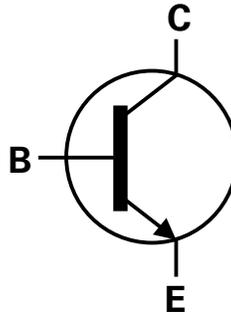
- Epitaxial Planar Die Construction
- Ideal for Low Power Amplification and Switching
- Complementary PNP Type: [MMBTA55](#) and [MMBTA56](#)
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **An automotive-compliant part is available under a separate datasheet ([MMBTA05Q/MMBTA06Q](#))**

## Mechanical Data

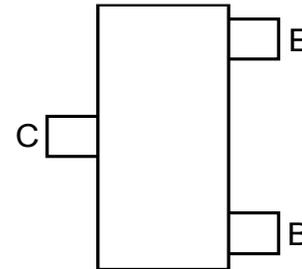
- Package: SOT23
- Package Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish – Matte Tin Plated Leads, Solderable per MIL-STD-202, Method 208 (E3)
- Weight: 0.008 grams (Approximate)



Top View



Device Symbol



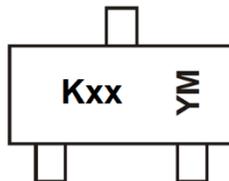
Top View  
Pin Configuration

## Ordering Information (Note 4)

Orderable Part Number	Package	Marking	Reel Size (inches)	Tape Width (mm)	Packing	
					Qty.	Carrier
MMBTA05-7-F	SOT23	K1G / K1H	7	8	3,000	Reel
MMBTA06-7-F	SOT23	K1G	7	8	3,000	Reel

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
  2. See <https://www.diodes.com/quality/lead-free/> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
  3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
  4. For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>.

## Marking Information



Kxx = Product Type Marking Code (See *Ordering Information*)  
 YM = Date Code Marking  
 Y or  $\bar{Y}$  or  $\underline{Y}$  = Year (ex: M = 2025)  
 M or  $\bar{M}$  = Month (ex: 9 = September)

### Date Code Key

Year	2005	-	2025	2026	2027	2028	2029	2030	2031	2032	2033	2034
Code	S	-	M	N	P	R	S	T	U	V	W	X

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

**Absolute Maximum Ratings** (@ $T_A = +25^\circ\text{C}$ , unless otherwise specified.)

Characteristic	Symbol	MMBTA05	MMBTA06	Unit
Collector-Base Voltage	$V_{CBO}$	60	80	V
Collector-Emitter Voltage	$V_{CEO}$	60	80	V
Emitter-Base Voltage	$V_{EBO}$	4.0		V
Collector Current	$I_C$	500		mA
Peak Collector Current	$I_{CM}$	1		A

**Thermal Characteristics** (@ $T_A = +25^\circ\text{C}$ , unless otherwise specified.)

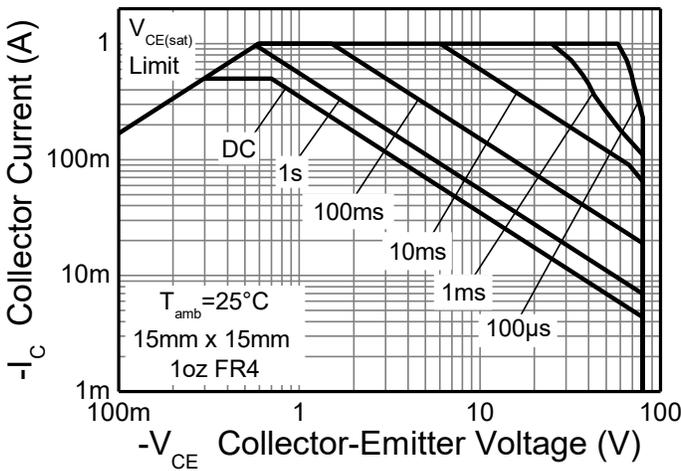
Characteristic	Symbol	Value	Unit
Power Dissipation	$P_D$	(Note 5)	310
		(Note 6)	350
Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	(Note 5)	403
		(Note 6)	357
Thermal Resistance, Junction to Leads	$R_{\theta JL}$	350	$^\circ\text{C/W}$
Thermal Resistance, Junction to Case	$R_{\theta JC}$	72	$^\circ\text{C/W}$
Operating and Storage Temperature Range	$T_J, T_{STG}$	-55 to +150	$^\circ\text{C}$

**ESD Ratings** (Note 8)

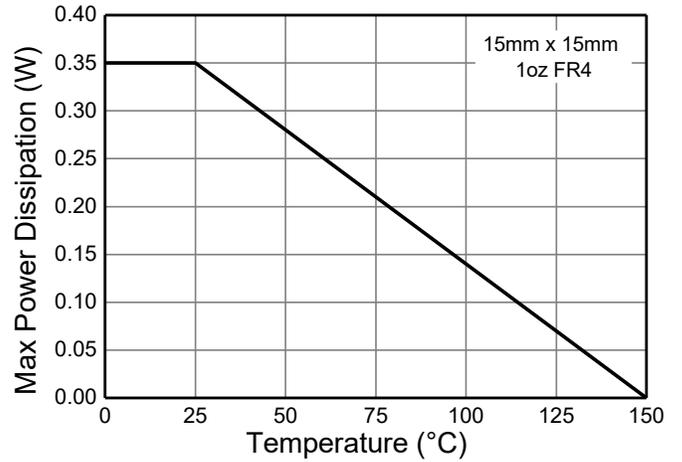
Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	400	V	C

- Notes:
5. For a device mounted on minimum recommended pad layout 1oz copper that is on a single-sided FR4 PCB; device is measured under still air conditions whilst operating in a steady state.
  6. Same as Note 5, except the device is mounted on 15mm x 15mm 1oz copper.
  7. Thermal resistance from junction to solder-point (at the end of the leads).
  8. Refer to JEDEC specifications JESD22-A114 and JESD22-A115.

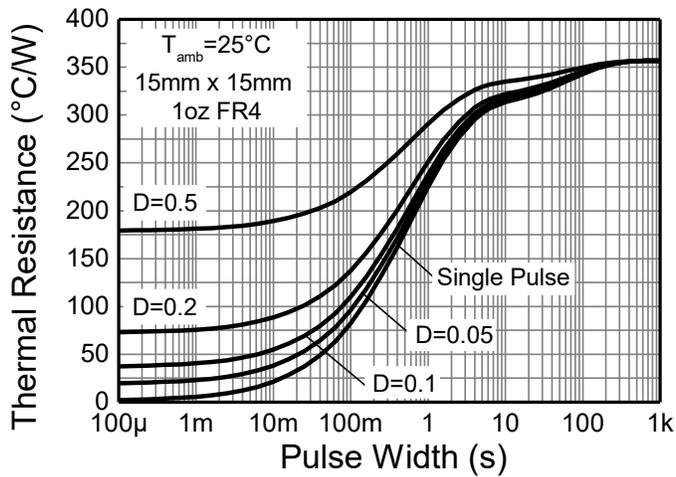
**Thermal Characteristics and Derating Information**



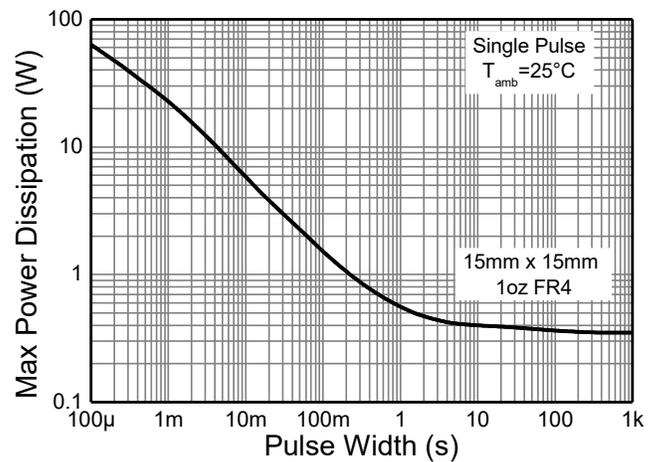
**Figure 1. Safe Operating Area**



**Figure 2. Derating Curve**



**Figure 3. Transient Thermal Impedance**



**Figure 4. Pulse Power Dissipation**

**Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Max	Unit	Test Condition	
<b>OFF CHARACTERISTICS</b>						
Collector-Base Breakdown Voltage	MMBTA05 MMBTA06	BV <sub>CBO</sub>	60 80	— —	V V	I <sub>C</sub> = 100μA, I <sub>E</sub> = 0
Collector-Emitter Breakdown Voltage (Note 9)	MMBTA05 MMBTA06	BV <sub>CEO</sub>	60 80	— —	V V	I <sub>C</sub> = 10.0mA, I <sub>B</sub> = 0
Emitter-Base Breakdown Voltage		BV <sub>EBO</sub>	4.0	—	V	I <sub>E</sub> = 100μA, I <sub>C</sub> = 0
Collector Cutoff Current	MMBTA05 MMBTA06	I <sub>CBO</sub>	—	100	nA	V <sub>CB</sub> = 60V, I <sub>E</sub> = 0 V <sub>CB</sub> = 80V, I <sub>E</sub> = 0
Collector Cutoff Current	MMBTA05 MMBTA06	I <sub>CES</sub>	—	100	nA	V <sub>CE</sub> = 60V, I <sub>BO</sub> = 0 V <sub>CE</sub> = 80V, I <sub>BO</sub> = 0
<b>ON CHARACTERISTICS (Note 9)</b>						
DC Current Gain		h <sub>FE</sub>	100	—	—	I <sub>C</sub> = 10mA, V <sub>CE</sub> = 1.0V I <sub>C</sub> = 100mA, V <sub>CE</sub> = 1.0V
Collector-Emitter Saturation Voltage		V <sub>CE(sat)</sub>	—	0.25	V	I <sub>C</sub> = 100mA, I <sub>B</sub> = 10mA
Base-Emitter Turn-On Voltage		V <sub>BE(on)</sub>	—	1.2	V	I <sub>C</sub> = 100mA, V <sub>CE</sub> = 1.0V
<b>SMALL-SIGNAL CHARACTERISTICS</b>						
Current Gain-Bandwidth Product		f <sub>T</sub>	100	—	MHz	V <sub>CE</sub> = 2.0V, I <sub>C</sub> = 10mA, f = 100MHz

Note: 9. Measured under pulsed conditions. Pulse width ≤ 300μs. Duty cycle ≤ 2%.

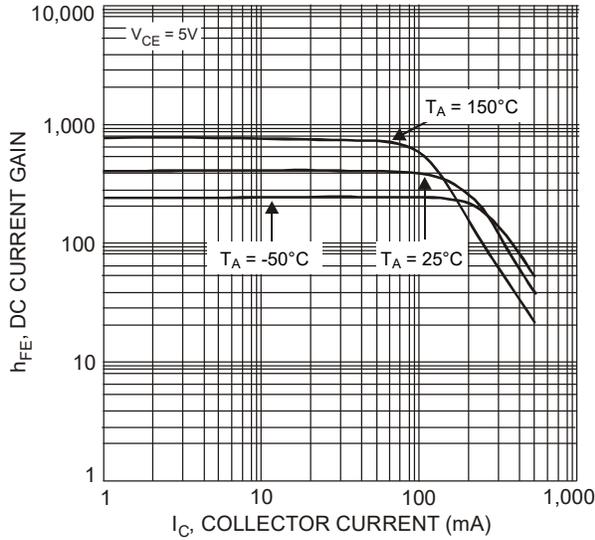


Figure 5. Typical DC Current Gain vs. Collector Current

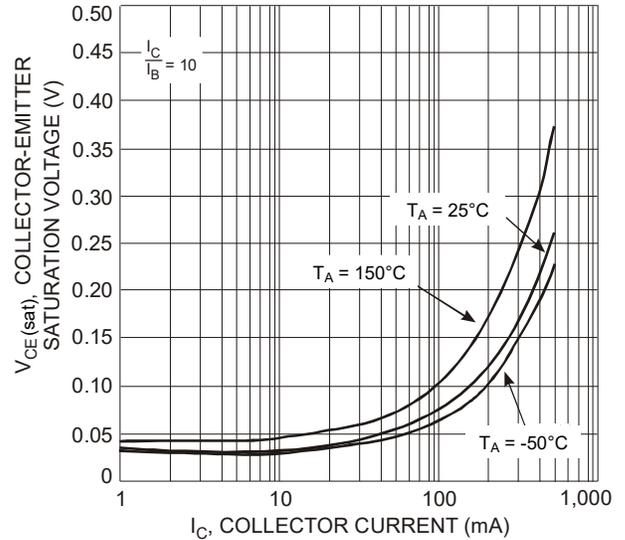


Figure 6. Collector-Emitter Saturation Voltage vs. Collector Current

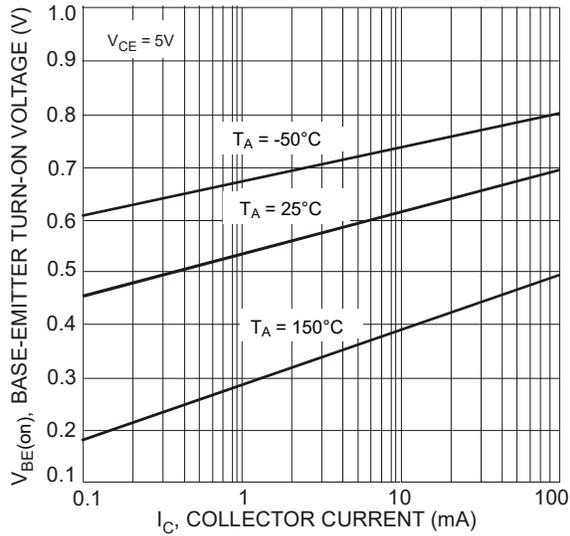


Figure 7. Typical Base-Emitter Turn-On Voltage vs. Collector Current

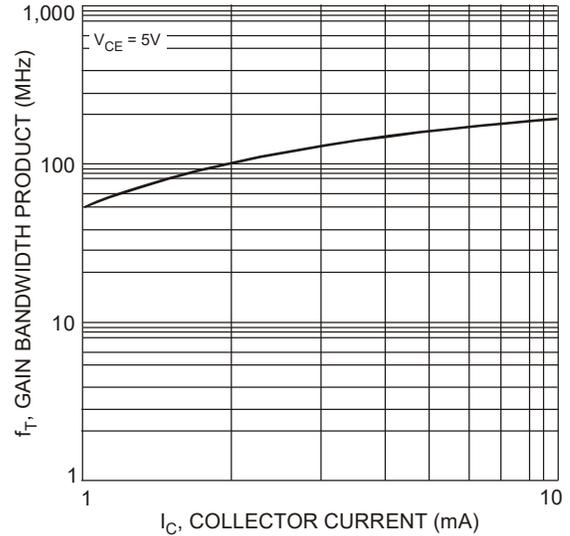


Figure 8. Typical Gain Bandwidth Product vs. Collector Current

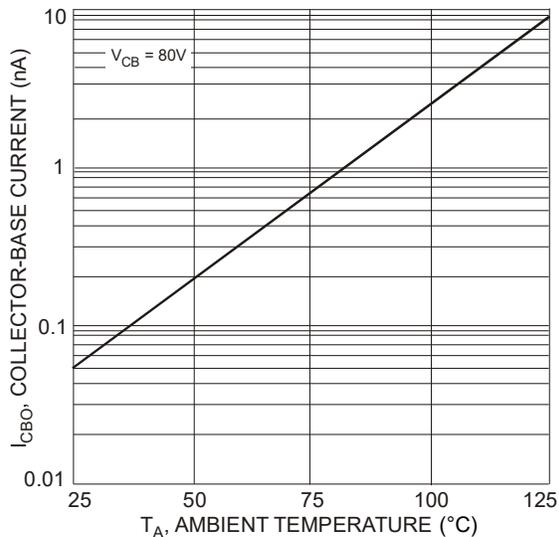


Figure 9. Typical Collector-Cutoff Current vs. Ambient Temperature

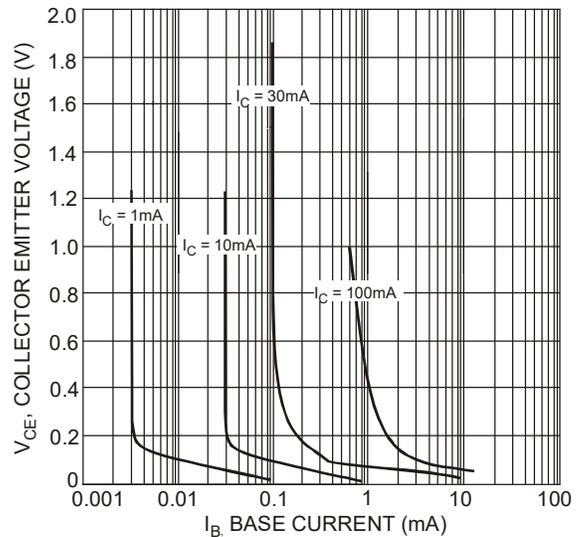
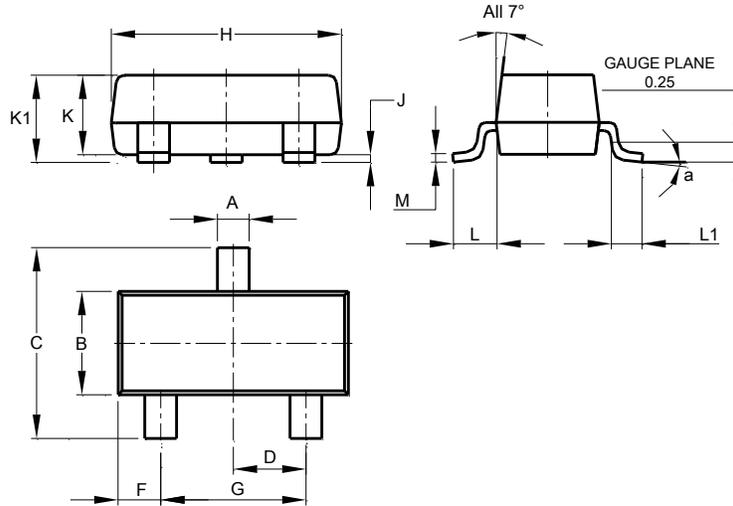


Figure 10. Typical Collector Saturation Region

## Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

**SOT23**

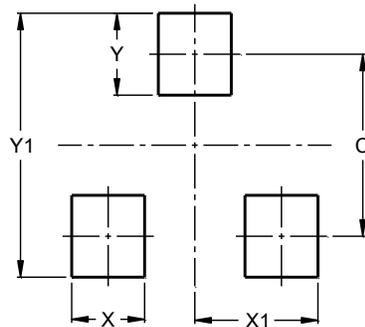


SOT23			
Dim	Min	Max	Typ
A	0.37	0.51	0.40
B	1.20	1.40	1.30
C	2.30	2.50	2.40
D	0.89	1.03	0.915
F	0.45	0.60	0.535
G	1.78	2.05	1.83
H	2.80	3.00	2.90
J	0.013	0.10	0.05
K	0.890	1.00	0.975
K1	0.903	1.10	1.025
L	0.45	0.61	0.55
L1	0.25	0.55	0.40
M	0.085	0.150	0.110
a	0°	8°	--
<b>All Dimensions in mm</b>			

## Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

**SOT23**



Dimensions	Value (in mm)
C	2.0
X	0.8
X1	1.35
Y	0.9
Y1	2.9

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